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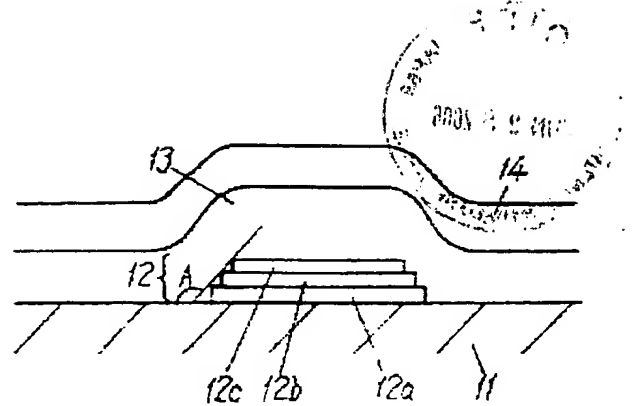
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INVENTOR : HOSOMI FUMIO;

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TITLE : THIN-FILM MULTILAYERED CIRCUIT BOARD AND ITS MANUFACTURE



ABSTRACT : PURPOSE: To prevent the disconnection of a second conductor layer and the occurrence of inter-layer leakage by improving the coating state of an insulating layer formed on a first conductor layer in a thin-film multilayered circuit board constituted by forming a thin-film multilayered circuit on a glass or alumina substrate.

CONSTITUTION: In a thin-film multilayered circuit board, a first-layer wiring 12 is formed as a first conductor layer by successively forming three thin films 12a, 12b, and 12c on an electrically insulating substrate 11 composed of glass and an layer insulating film 13 and second-layer wiring 14 are successively formed on the wiring 12 as an insulating layer and second conductor layer, respectively. The widths of the thin films 12a, 12b, and 12c are reduced as going toward the topmost layer 12c so that steps can be formed on the outer peripheral surface of the wiring 12.

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